

Appl. No. 10/812,889  
Amdt. Dated: 07/06/06  
Reply to Office action of 05/25/06

**Amendment to the Specification:**

Page 1 – please amend the first paragraph as follows:

In S.N.       /      ,       10/812,890, entitled, “Circuitized Substrate, Method Of Making Same, Electrical Assembly Utilizing Same, And Information Handling System Utilizing Same”, filed concurrently herewith (inventors: R. Japp et al), there is defined a circuitized substrate, electrical assembly and information handling system capable of utilizing dielectric layers made using the dielectric composition taught herein. A method of making the substrate is also defined in this co-pending application.